



Press Release

ThinPAK 5x6 Brings Smallest CoolMOS™ MOSFETs Ever into Adapters, Consumer Electronics and Lighting Applications

Neubiberg, Germany – May 15, 2014 – Infineon Technologies today introduces a new leadless surface mounted (SMD) package for CoolMOS™ MOSFETs named ThinPAK 5x6.

Chargers for mobile devices, Ultra High Definition TVs and LED lighting all have to meet numerous conflicting requirements. Consumers long for slim yet high performing products. Therefore, manufacturers demand compact, cool and cost efficient semiconductor solutions. These considerable space constraints can be resolved by reducing the size and weight of the components which occupy printed circuit board (PCB) area.

The worldwide smartphone market, for instance, is expected to grow by 9.4 percent year over year (2013 – 2018), according to Strategy Analytics (2014).

For chargers, there is a clear trend towards smaller, faster and more efficient solutions. With its height of only 1mm and with its very small footprint of 5mm x 6 mm the ThinPAK 5x6 provides 80 percent volume reduction in comparison to traditional SMD packages such as DPAK. Thus, manufacturers gain flexibility for the design of even smaller chargers. The very low parasitics of ThinPAK – such as low source inductance compared to the traditional DPAK – reduce the gate oscillation under all load conditions and minimize voltage overshoots during switching by 40 percent in comparison to traditional SMD thus improving device and system stability and ease of use.

The ThinPAK 5x6 guarantees engineers more flexibility in their PCB designs and better switching performance ultimately leading to more efficient power conversion while reducing overall system size in applications such as low power adapters, lighting and thin panel TVs. It follows the earlier release of the ThinPAK 8x8 which

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has meanwhile found excellent market adoption in higher power applications such as Server and Telecom SMPS.

Availability

Engineering samples of the ThinPAK 5x6 package are available now. Volume production will begin in September 2014. For additional information on Infineon's ThinPAK 5x6 package please visit www.infineon.com/ThinPAK5x6

Infineon at the PCIM

Infineon is presenting the ThinPAK 5x6 at booth 311 in hall 9 at the PCIM trade fair being held in Nuremberg from May 20 to 22, 2014. Further information about the highlights of the trade fair is to be found at www.infineon.com/PCIM2014.

About Infineon

[Infineon](http://www.infineon.com) Technologies AG, Neubiberg, Germany, offers semiconductor and system solutions addressing three central challenges to modern society: [energy efficiency](#), [mobility](#), and [security](#). In the 2013 fiscal year (ending September 30), the company reported sales of Euro 3.84 billion with close to 26,700 employees worldwide. Infineon is listed on the Frankfurt Stock Exchange (ticker symbol: IFX) and in the USA on the over-the-counter market OTCQX International Premier (ticker symbol: IFNNY).

Further information is available at www.infineon.com

This news release is available online at www.infineon.com/press

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